



## Material Content Data Sheet



<b>Sales Product Name</b>		SPU02N60C3		<b>Issued</b>		2. August 2018		
<b>MA#</b>		MA000851400						
<b>Package</b>		PG-TO251-3-21		<b>Weight*</b>		349.77 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.473	0.42	0.42	4211	4211
leadframe	non noble metal	tin	7440-31-5	0.273	0.08		781	
	non noble metal	copper	7440-50-8	181.882	52.00	52.08	520011	520792
wire	non noble metal	aluminium	7429-90-5	0.464	0.13	0.13	1326	1326
encapsulation	organic material	carbon black	1333-86-4	1.357	0.39		3881	
	inorganic material	antimonytrioxide	1309-64-4	2.838	0.81		8115	
	plastics	brominated resin	-	3.209	0.92		9173	
	plastics	epoxy resin	-	23.447	6.70		67037	
	inorganic material	silicondioxide	60676-86-0	92.555	26.46	35.28	264618	352824
leadfinish	non noble metal	tin	7440-31-5	3.976	1.14	1.14	11366	11366
plating	non noble metal	nickel	7440-02-0	0.344	0.10	0.10	984	984
solder	noble metal	silver	7440-22-4	0.044	0.01		127	
	non noble metal	tin	7440-31-5	0.036	0.01		102	
	non noble metal	lead	7439-92-1	1.697	0.49	0.51	4853	5082
heatspreader	non noble metal	iron	7439-89-6	0.036	0.01		103	
	inorganic material	phosphorus	7723-14-0	0.011	0.00		31	
	non noble metal	copper	7440-50-8	36.124	10.33	10.34	103281	103415
*deviation	< 10%		Sum in total:			100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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